

## TECHNICAL DATA SHEET

# Thermal conductive paste **Silver**

An innovative solution that ensures efficient heat dissipation from electronic components. With a thermal conductivity of >3.8 W/mK and silver content, this product guarantees reliability and high performance across a wide range of applications, from processor cooling to heating systems. Designed for professionals and technology enthusiasts, Silver Paste minimizes thermal resistance and extends the lifespan of devices.

#### **Product features:**

- thermal conductivity >3.8 W/mK,
- high temperature resistance,
- excellent dielectric properties,
- versatile applications,
- easy application,
- compliance with RoHS directive.

#### **Applications:**

- cooling systems for computers and industrial devices,
- vacuum solar collectors,
- LED diodes,
- components requiring high-temperature resistance.

Physicochemical properties	
Appearance	Silver paste
Density at 20°C	2.37 g/cm <sup>3</sup>
Thermal conductivity	>3.8 W/mK
Operating temperature range	-50°C to 250°C
Thermal impedance	<0.067°C in²/W
Evaporation	<0.001%
Viscosity	Does not flow
Thixotropic index	380±10
Electrical strength	500 V/mm
Volume resistivity (ASTM D257)	2.9*10 <sup>11</sup> p, Ω x m 2.9*10 <sup>13</sup> Ω x cm
Dielectric loss factor tg δ (ASTM D150)	<ul> <li>&lt;0.001 (120 Hz)</li> <li>0.003 (1 kHz)</li> <li>&lt;0.001 (10 kHz)</li> <li>&lt;0.001 (100 kHz)</li> </ul>
Relative dielectric permeability $\epsilon_r$ (ASTM D150)	13.9 (120 Hz) 14.0 (1 kHz) 13.9 (10 kHz) 13.8 (100 kHz)
Shelf life	3 years





AG TermoPasty Grzegorz Gąsowski ul. Kolejowa 33 E, 18-218 Sokoły, tel. +48 86 274 13 42, info@termopasty.pl, www.termopasty.com



# TECHNICAL DATA SHEET

#### Compatibility:

Silver Paste is safe for use with most materials. Its viscosity prevents movement, making application easier and ensuring stability in all conditions.

Application method		
Machine application	Yes	
Sachet	Yes	
Syringe	Yes	
Stencil	Yes	
Spatula	Yes	

#### **Usage instructions:**

### Restricted to professional users. Read SDS carefully prior to use.

Before application, ensure that surfaces are clean and dry. Apply a small amount of thermal paste to the center of the electronic component. Using an included spatula, spread an even, thin layer across the entire contact surface. Do not use excessive paste—just enough to ensure efficient heat transfer. Then, mount the heat sink or other cooling component.

For 100 g and 1 kg packaging, mix the paste thoroughly before application. Stir for about 1-2 minutes, paying special attention to reaching the bottom of the container. This ensures proper mixing of the ingredients and optimal product performance.

Package		
Sachet	0,5 g (ART.AGT-143) - 20/200 pcs.*	
Syringe	1 g (ART.AGT-164) - 5 pcs.* 3 g (ART.AGT-107) - 5 pcs.*	
Plastic box	100 g (ART.AGT-118) - 1 pc.* 1 kg (ART.AGT-149) - 1 pc.*	

\*Quantity of pcs. in a bulk package

#### Storage:

Store in a well-ventilated, cool, and dry place. Keep containers tightly closed when not in use. Protect from direct sunlight.

#### **Technical support:**

AG TermoPasty provides technical support, answering questions about the technical specifications and applications of our products. Please contact us via email at info@termopasty.pl.

#### Note:

The data presented in this document reflect our current state of knowledge and describe the typical properties and applications of the product. However, the responsibility for determining the suitability of this product for specific applications lies with the user. AG TermoPasty is not liable for the results of the product's use, as the conditions of its application are beyond our control.

AG TermoPasty Grzegorz Gąsowski ul. Kolejowa 33 E, 18-218 Sokoły, tel. +48 86 274 13 42, info@termopasty.pl, www.termopasty.com